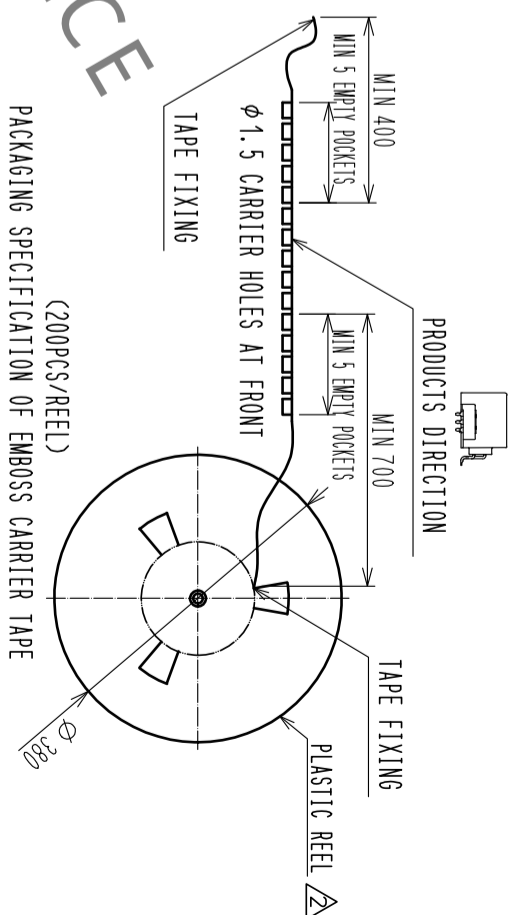
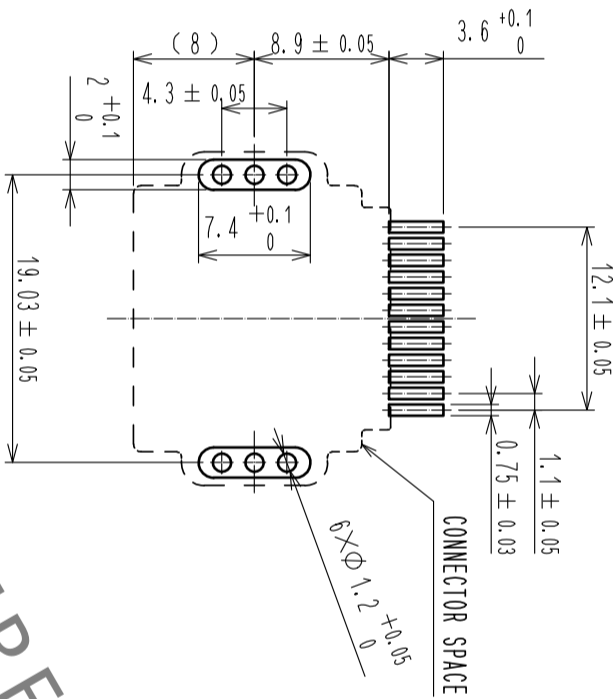
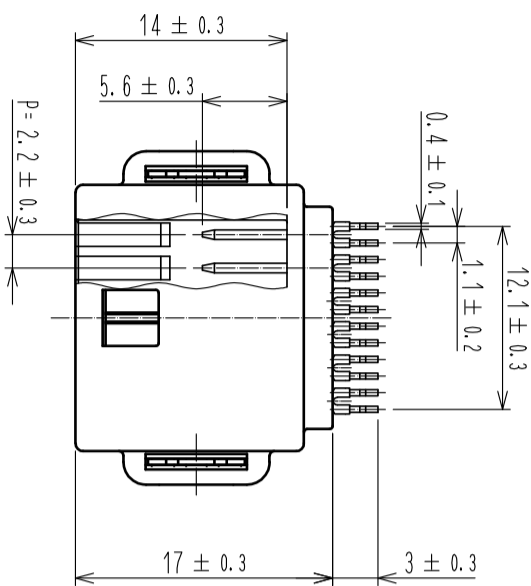
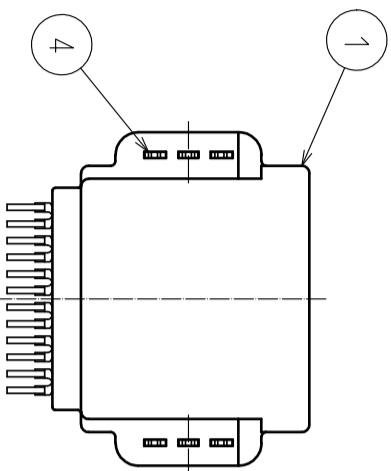
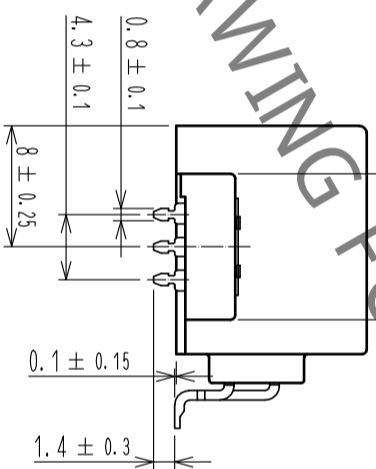
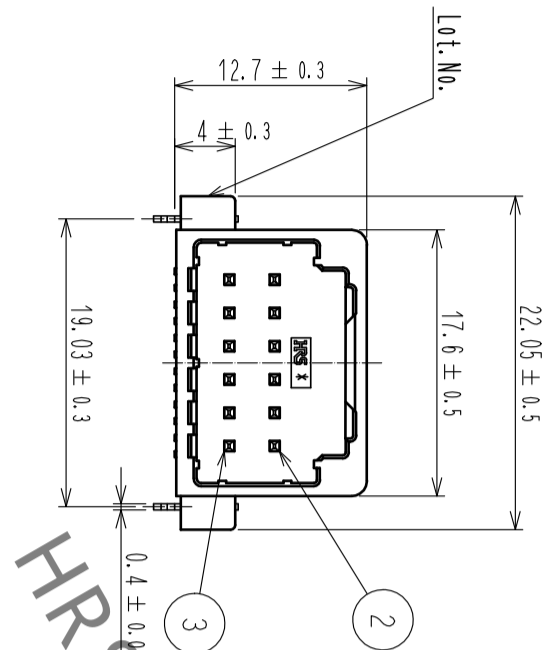


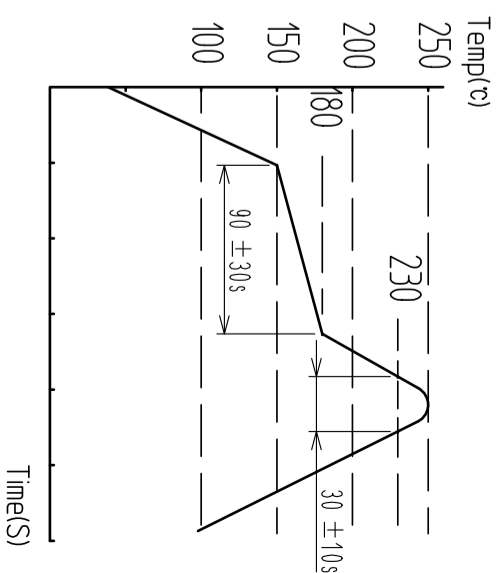
ELV, ROHS COMPLIANT



RECOMMENDED PCB PATTERN



- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.)
 REFLOW HEATING METHOD : IR IN THE AIR OR NITROGEN
 NO. OF CYCLES : 2 MAX
 PEAK : 250°C
 OVER 230°C : 20~40s
 PREHEAT : 150~180°C
 60~120s
2. TEMPERATURE FOR SOLDERING IRON : 280~300°C MAX WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1mm MAX.
 4. PC BOARD THICKNESS = 1.6mm
 5. RECOMMENDED SOLDER THICKNESS = 0.15mm



2	BRASS	TIN PLATED T=0.64	4	BRASS	TIN PLATED T=0.4
1	PPS	LIGHT GRAY	3	BRASS	TIN PLATED T=0.64
MATERIAL		FINISH . REMARKS	MATERIAL		FINISH . REMARKS
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	CHECKED	DATE
mm	2 : 1	1	DIS-T-000006398	DONGCHAN KIM	20200722
APPROVED : K.S. SATOH		DRAWING NO.		EDC-166407-00-00	
CHECKED : AR. SHIRAI		PART NO.		GT25-12DP-2.2H	
DESIGNED : TY. SAKASHITA		DRAWN		CL775-0005-4-00	
HRS		HIROSE ELECTRIC CO., LTD.		1/1	